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See <http://cyberscitech.net/2017/>, <http://cse.stfx.ca/~dasc2017/>,

<http://cse.stfx.ca/~picom2017/>,

<http://grid.chu.edu.tw/datacom2017>

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***IEEE CyberSciTech 2017*, DASC 2017, PICom 2017 and DataCom 2017**

**Orlando, USA**

**November 6-10, 2017**

**http://cyberscitech.net/2017/, http://cse.stfx.ca/~dasc2017/,**

**http://cse.stfx.ca/~picom2017/, http://grid.chu.edu.tw/datacom2017**

The modern digitized world has led to the emergence of a new paradigm on global information networks and infrastructures known as Cyberspace and the studies of Cybernetics, which bring seamless integration of physical, social and mental spaces. Cyberspace is becoming an integral part of our daily life from learning and entertainment to business and cultural activities. As expected, this whole concept of Cybernetics brings new challenges that need to be tackled. The 2017 IEEE Cyber Science and Technology Congress (**CyberSciTech** **2017**) offers a common platform for scientists, researchers and engineers to share their latest ideas and to exchange the latest developments and outcomes in their research and technologies, with a broad scope of cyber-related science, technology and application topics.

Papers for **CyberSciTech 2017** should be prepared in IEEE CS Proceedings format and submitted to <https://edas.info/newPaper.php?c=23118>

**DASC 2017** will be held in November 6-10, 2017 in Orlando, Florida, USA. It aims to bring together computer scientists, industrial engineers, and researchers to discuss and exchange experimental and theoretical results, novel designs, work-in-progress, experience, case studies, and trend-setting ideas in the areas of dependability, security, trust and/or autonomic computing systems. Papers for **DASC 2017** should be prepared in IEEE CS Proceedings format and submitted via website: <http://cse.stfx.ca/~dasc2017/sub/>.

Over the last fifty years, computational intelligence has evolved from logic-based artificial intelligence, nature-inspired soft computing, social-oriented agent technology to cyber-physical integrated ubiquitous intelligence towards Pervasive Intelligence (PI). **PICom 2017** aims to bring together computer scientists & engineers, to discuss and exchange experimental and theoretical results, work-in-progress, novel designs, and test-environments or test-beds in the areas of Pervasive Intelligence and Computing.

Papers for **PICom 2017** should be prepared in IEEE CS Proceedings format and submitted via website: <http://cse.stfx.ca/~picom2017/ps.php>.

The goal of IEEE **DataCom 2017** is to establish an international forum for engineers and scientists to present their ideas and experiences in the fields of Big Data intelligence and computing. IEEE DataCom 2017 welcomes paper submissions on innovative work from researchers in academia, industry and government describing original research work in Big Data.

Papers for **DataCom 2017** should be prepared in IEEE CS Proceedings format and submitted via website: <https://easychair.org/conferences/?conf=ieeedatacom2017>.

**Important Dates**

**Research Paper Submission Due: July 24, 2017**

**Author Notification: August 20, 2017**

**Workshop/Poster/WIP/Special Session Submission Due: August 15, 2017**

**Author Notification: August 31, 2017**

**All Paper Registration Due: September 17, 2017**

**All Camera-Ready Manuscript Due: September 21, 2017**

**Work**

**Submission and Publication**

Authors are invited to submit their original work that has not previously been submitted or published in any other venue. Submitted papers need to abide by IEEE Computer Society formats. Final papers must be formatted accordingly (see “[IEEE Manuscript Templates](http://www.ieee.org/conferences_events/conferences/publishing/templates.html)”) .

Regular, work-in-progress, workshop/special session, poster (short) papers all need to be in IEEE CS format and submitted following the same instruction on the websites. A regular, workshop, or special session paper should be between 6-8 pages. A work-in-progress paper should be between 4-6 pages whereas a poster (short) paper should be between 2-4 pages.

All accepted papers in the regular, work-in-progress, workshops, special sessions and posters will be published in an IEEE Computer Society proceedings (EI indexed). Extended versions of selected excellent papers will be considered for publication in special issues of prestige journals (SCI/EI indexed).